## A1140/41/42/43

# Sensitive Two-Wire Chopper-Stabilized Unipolar Hall Effect Switches 


Package UA, 3-pin SIP


| ABSOLUTE MAXIMUM RATINGS |
| :---: |
| Supply Voltage, $\mathrm{V}_{\mathrm{CC}}$............................... 28 V |
|  |
| Magnetic Flux Density, B ....................Unlimited |
| Power Dissipation, $\mathrm{P}_{\mathrm{D}}$........................Graph, p. 5 |
| Operating Temperature |
| Ambient, $\mathrm{T}_{\mathrm{A}}$, Range E..............-40 ${ }^{\circ} \mathrm{C}$ to $\mathbf{8 5}^{\circ} \mathrm{C}$ |
| Ambient, $\mathrm{T}_{\mathrm{A}}$, Range L.............. $\mathbf{4 0}^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$ |
| Maximum Junction, $\mathrm{T}_{\mathrm{J}(\max )} \ldots \ldots . . . . . . . . . . . . . . .1655^{\circ} \mathrm{C}$ |
| Storage Tem |

The A1140, A1141, A1142, and A1143 devices are sensitive, two-wire, unipolar, Hall effect switches that are factory-programmed at end-of-line to optimize magnetic switchpoint accuracy. These devices use a patented high frequency chop-per-stabilization technique, produced using the Allegro advanced BiCMOS wafer fabrication process, to achieve magnetic stability and to eliminate offset inherent in single-element devices exposed to harsh application environments.

Commonly found in a number of automotive applications, these switches are utilized to sense seat track position, seat belt buckle presence, hood/trunk latching, and shift selector position. Two-wire unipolar switches, such as the A1140/41/42/43 family, are particularly advantageous in price-sensitive applications because they require one less wire for operation than do switches with the more traditional open-collector output. Additionally, the system designer inherently gains diagnostics because there is always output current flowing, which should be in either of two narrow ranges. Any current level not within these ranges indicates a fault condition. The A1140/41/42/43 family of switches also features on-chip transient protection and a Zener clamp to protect against overvoltage conditions on the supply line.

The output currents of the A1141 and A1143 switch HIGH in the presence of a south $(+)$ polarity magnetic field of sufficient strength, and switch LOW otherwise, as in the presence of a weak field or a north $(-)$ polarity field. The other two devices in the family (A1140 and A1142) have an opposite output: the currents switch LOW in the presence of a south-polarity magnetic field of sufficient strength, and switch HIGH otherwise. The other differences in the switches are their defined low current levels and magnetic switchpoints.

All versions are offered in two package styles. The LH is a SOT-23W, miniature low-profile package for surface-mount applications. The UA is a three-lead ultramini SIP for through-hole mounting. Each package is available in a lead ( Pb ) free version (suffix, $-T$ ) with $100 \%$ matte tin plated leadframe. Field-programmable versions also available: A1180, A1181, A1182, and A1183.

## Features and Benefits

- Chopper stabilization
- Low switchpoint drift over operating temperature range
- Low sensitivity to stress

■ Factory programmed at end-of-line for optimized switchpoints

■ On-chip protection

- Supply transient protection
- Reverse-battery protection
- On-board voltage regulator
- 3.5 to 24 V operation

Functional Block Diagram


Package LH, 3-pin SOT
Package UA, 3-pin SIP


ELECTRICAL CHARACTERISTICS over the operating voltage and temperature ranges, unless otherwise specified

| Characteristic | Symbol | Test Conditions | Min. | Typ. | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Supply Voltage ${ }^{1}$ | $\mathrm{V}_{\mathrm{CC}}$ |  | 3.5 | - | 24 | V |
| Supply Current ${ }^{2}$ | $\mathrm{I}_{\mathrm{CC}(\mathrm{L})}$ | $\mathrm{B}>\mathrm{B}_{\mathrm{OP}}$ for A 1140 ; $\mathrm{B}<\mathrm{B}_{\mathrm{RP}}$ for A 1141 | 2 | - | 5 | mA |
|  |  | $B>B_{O P}$ for $A 1142 ; B<B_{R P}$ for $A 1143$ | 5 | - | 6.9 | mA |
|  | $\mathrm{I}_{\mathrm{CC}(\mathrm{H})}$ | $B>B_{\text {OP }}$ for A1141, A1143 $B<B_{R P}$ for $A 1140, A 1142$ | 12 | -- | 17 | mA |
| Reverse Supply Current | $\mathrm{I}_{\text {RCC }}$ | $\mathrm{V}_{\mathrm{RCC}}=-18 \mathrm{~V}$ | - | - | -1.6 | mA |
| Supply Zener Clamp Voltage | V ZSUPPLY | $\mathrm{I}_{\mathrm{CC}}=\mathrm{I}_{\mathrm{CCL}(\max )}+3 \mathrm{~mA} ; \mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | 28 | - | 40 | V |
| Supply Zener Clamp Current ${ }^{3}$ | İZSUPPLY | $\mathrm{V}_{\text {ZSUPPLY }}=28 \mathrm{~V}$ | - | - | 10 | mA |
| Output Slew Rate ${ }^{4}$ | di/dt | Capacitance of the oscilloscope performing the measurement $=20 \mathrm{pF}$ | - | 36 | - | $\mathrm{mA} / \mu \mathrm{s}$ |
| Chopping Frequency | $\mathrm{f}_{\mathrm{C}}$ |  | - | 200 | - | kHz |
| Power-On Time ${ }^{5}$ | $\mathrm{t}_{\text {on }}$ | $\mathrm{C}_{\text {BYPASS }}=0.01 \mu \mathrm{~F}$ | - | - | 25 | $\mu \mathrm{s}$ |
| Power-On State ${ }^{6,7}$ | POS | $\mathrm{t}<\mathrm{t}_{\mathrm{on}} ; \mathrm{V}_{\text {cC }}$ slew rate $>25 \mathrm{mV} / \mu \mathrm{s}$ | - | HIGH | - | - |

${ }^{1} V_{C C}$ represents the generated voltage between the VCC pin and the GND pin.
${ }^{2}$ Relative values of $B$ use the algebraic convention, where positive values indicate south magnetic polarity, and negative values indicate north magnetic polarity; therefore greater $B$ values indicate a stronger south polarity field (or a weaker north polarity field, if present).
$3 I_{\mathrm{ZSUPPLY}(\max )}=\mathrm{I}_{\mathrm{CCL}(\max )}+3 \mathrm{~mA}$.
${ }^{4}$ Measured without bypass capacitor between VCC and GND. Use of a bypass capacitor results in slower current change.
${ }^{5}$ Measured with and without bypass capacitor of $0.01 \mu \mathrm{~F}$. Adding a larger bypass capacitor causes longer Power-On Time.
${ }^{6} P O S$ is defined as true only with a $V_{C C}$ slew rate of $25 \mathrm{mV} / \mu \mathrm{s}$ or greater. Operation with a $V_{C C}$ slew rate less than $25 \mathrm{mV} / \mu \mathrm{s}$ can permanently harm device performance.
${ }^{7} \mathrm{POS}$ is undefined for $\mathrm{t}>\mathrm{t}_{\text {on }}$ or $\mathrm{B}_{\mathrm{RP}}<\mathrm{B}<\mathrm{B}_{\mathrm{OP}}$.

MAGNETIC CHARACTERISTICS over the operating voltage and temperature ranges, unless otherwise specified

| Characteristic | Symbol |  | est Conditions | Min. | Typ.* | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Operate Point | $\mathrm{B}_{\mathrm{OP}}$ | A1140, A1142 | $\mathrm{I}_{\mathrm{CC}}=\mathrm{I}_{\mathrm{CCL}}$ | 50 | 80 | 115 | G |
|  |  | A1141, A1143 | $\mathrm{I}_{\mathrm{CC}}=\mathrm{I}_{\mathrm{CCH}}$ |  |  |  |  |
| Release Point | $\mathrm{B}_{\mathrm{RP}}$ | A1140, A1142 | $\mathrm{I}_{\mathrm{CC}}=\mathrm{I}_{\mathrm{CCH}}$ | 45 | 65 | 110 | G |
|  |  | A1141, A1143 | $\mathrm{I}_{\mathrm{CC}}=\mathrm{I}_{\mathrm{CCL}}$ |  |  |  |  |
| Hysteresis | $\mathrm{B}_{\mathrm{HYS}}$ | $\mathrm{B}_{\mathrm{HYS}}=\mathrm{B}_{\mathrm{OP}}-\mathrm{B}_{\mathrm{RP}}$ |  | 5 | 15 | 30 | G |

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## A1140/41/42/43

## Sensitive Two-Wire Chopper-Stabilized Unipolar Hall Effect Switches

## Characteristic Data





## A1140/41/42/43

## Sensitive Two-Wire Chopper-Stabilized Unipolar Hall Effect Switches

THERMAL CHARACTERISTICS may require derating at maximum conditions, see application information

| Characteristic | Symbol | Test Conditions | Value | Units |
| :---: | :---: | :---: | :---: | :---: |
| Package Thermal Resistance | $\mathrm{R}_{\theta \mathrm{JA}}$ | Package LH, minimum-K PCB (single layer, single-sided with copper limited to solder pads) | 110 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
|  |  | Package LH, low-K PCB (single layer, double-sided with 0.926 in $^{2}$ copper area) | 228 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
|  |  | Package UA, minimum-K PCB (single layer, single-sided with copper limited to solder pads) | 165 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |




## Sensitive Two-Wire Chopper-Stabilized Unipolar Hall Effect Switches

## Functional Description

## Operation

The output, $\mathrm{I}_{\mathrm{CC}}$, of the A1140 and A1142 devices switch low after the magnetic field at the Hall sensor exceeds the operate point threshold, $\mathrm{B}_{\mathrm{OP}}$. When the magnetic field is reduced to below the release point threshold, $\mathrm{B}_{\mathrm{RP}}$, the device output goes high. The differences between the magnetic operate and release point is called the hysteresis of the device, $\mathrm{B}_{\mathrm{HYS}}$. This built-
in hysteresis allows clean switching of the output even in the presence of external mechanical vibration and electrical noise. The A1141 and A1143 devices switch with opposite polarity for similar $\mathrm{B}_{\mathrm{OP}}$ and $\mathrm{B}_{\mathrm{RP}}$ values, in comparison to the A 1140 and A1142 (see figure 1).


Figure 1. Alternative switching behaviors are available in the A114x device family. On the horizontal axis, the B+ direction indicates increasing south polarity magnetic field strength, and the $B$ - direction indicates decreasing south polarity field strength (including the case of increasing north polarity).

## Chopper Stabilization Technique

When using Hall-effect technology, a limiting factor for switchpoint accuracy is the small signal voltage developed across the Hall element. This voltage is disproportionally small relative to the offset that can be produced at the output of the Hall sensor. This makes it difficult to process the signal while maintaining an accurate, reliable output over the specified operating temperature and voltage ranges.

Chopper stabilization is a unique approach used to minimize Hall offset on the chip. The patented Allegro technique, namely Dynamic Quadrature Offset Cancellation, removes key sources of the output drift induced by thermal and mechanical stresses. This offset reduction technique is based on a signal modulationdemodulation process. The undesired offset signal is separated from the magnetic field-induced signal in the frequency domain, through modulation. The subsequent demodulation acts as a modulation process for the offset, causing the magnetic fieldinduced signal to recover its original spectrum at baseband, while the dc offset becomes a high-frequency signal. The magneticsourced signal then can pass through a low-pass filter, while the modulated dc offset is suppressed. This configuration is illustrated in figure 2.

The chopper stabilization technique uses a 200 kHz high frequency clock. For demodulation process, a sample and hold technique is used, where the sampling is performed at twice the chopper frequency ( 400 kHz ). This high-frequency operation allows a greater sampling rate, which results in higher accuracy and faster signal-processing capability. This approach desensitizes the chip to the effects of thermal and mechanical stresses, and produces devices that have extremely stable quiescent Hall output voltages and precise recoverability after temperature cycling. This technique is made possible through the use of a BiCMOS process, which allows the use of low-offset, low-noise amplifiers in combination with high-density logic integration and sample-and-hold circuits.

The repeatability of magnetic field-induced switching is affected slightly by a chopper technique. However, the Allegro highfrequency chopping approach minimizes the affect of jitter and makes it imperceptible in most applications. Applications that are more likely to be sensitive to such degradation are those requiring precise sensing of alternating magnetic fields; for example, speed sensing of ring-magnet targets. For such applications, Allegro recommends its digital sensor families with lower sensitivity to jitter. For more information on those devices, contact your Allegro sales representative.


Figure 2. Chopper stabilization circuit (Dynamic Quadrature Offset Cancellation)

## Sensitive Two-Wire Chopper-Stabilized Unipolar Hall Effect Switches

## Application Information

## Typical Application Circuit

The A114x family of devices must be protected by an external bypass capacitor, $\mathrm{C}_{\mathrm{BYP}}$, connected between the supply, VCC , and the ground, GND, of the device. $\mathrm{C}_{\mathrm{BYP}}$ reduces both external noise and the noise generated by the chopper-stabilization function. As shown in figure 3 , a $0.01 \mu \mathrm{~F}$ capacitor is typical.

Installation of $\mathrm{C}_{\mathrm{BYP}}$ must ensure that the traces that connect it to the A114x pins are no greater than 5 mm in length.

All high-frequency interferences conducted along the supply lines are passed directly to the load through $\mathrm{C}_{\mathrm{BYP}}$, and it serves only to protect the A114x internal circuitry. As a result, the load ECU (electronic control unit) must have sufficient protection, other than $\mathrm{C}_{\mathrm{BYP}}$, installed in parallel with the A 114 x .

A series resistor on the supply side, RS (not shown), in combination with $\mathrm{C}_{\mathrm{BYP}}$, creates a filter for EMI pulses.

When determining the minimum $\mathrm{V}_{\mathrm{CC}}$ requirement of the A 114 x device, the voltage drops across $\mathrm{R}_{\mathrm{S}}$ and the ECU sense resistor, $\mathrm{R}_{\text {SENSE }}$, must be taken into consideration. The typical value for $\mathrm{R}_{\text {SENSE }}$ is approximately $100 \Omega$.


Figure 3. Typical application circuit

For additional general application information, visit the Allegro
Web site at www. allegromicro.com.

## Sensitive Two-Wire Chopper-Stabilized Unipolar Hall Effect Switches

## Power Derating

The device must be operated below the maximum junction temperature of the device, $\mathrm{T}_{\mathrm{J}(\max )}$. Under certain combinations of peak conditions, reliable operation may require derating supplied power or improving the heat dissipation properties of the application. This section presents a procedure for correlating factors affecting operating $\mathrm{T}_{\mathrm{J}}$. (Thermal data is also available on the Allegro MicroSystems Web site.)

The Package Thermal Resistance, $\mathrm{R}_{\theta \mathrm{JA}}$, is a figure of merit summarizing the ability of the application and the device to dissipate heat from the junction (die), through all paths to the ambient air. Its primary component is the Effective Thermal Conductivity, K , of the printed circuit board, including adjacent devices and traces. Radiation from the die through the device case, $\mathrm{R}_{\theta \mathrm{JC}}$, is relatively small component of $\mathrm{R}_{\theta \mathrm{JA}}$. Ambient air temperature, $\mathrm{T}_{\mathrm{A}}$, and air motion are significant external factors, damped by overmolding.
The effect of varying power levels (Power Dissipation, $\mathrm{P}_{\mathrm{D}}$ ), can be estimated. The following formulas represent the fundamental relationships used to estimate $T_{J}$, at $\mathrm{P}_{\mathrm{D}}$.

$$
\begin{gather*}
\mathrm{P}_{\mathrm{D}}=\mathrm{V}_{\mathrm{IN}} \times \mathrm{I}_{\mathrm{IN}}  \tag{1}\\
\Delta \mathrm{~T}=\mathrm{P}_{\mathrm{D}} \times \mathrm{R}_{\theta \mathrm{JA}}  \tag{2}\\
\mathrm{~T}_{\mathrm{J}}=\mathrm{T}_{\mathrm{A}}+\Delta \mathrm{T} \tag{3}
\end{gather*}
$$

For example, given common conditions such as: $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, $\mathrm{V}_{\mathrm{CC}}=12 \mathrm{~V}, \mathrm{I}_{\mathrm{CC}}=4 \mathrm{~mA}$, and $\mathrm{R}_{\theta \mathrm{JA}}=140^{\circ} \mathrm{C} / \mathrm{W}$, then:

$$
\begin{aligned}
& \mathrm{P}_{\mathrm{D}}=\mathrm{V}_{\mathrm{CC}} \times \mathrm{I}_{\mathrm{CC}}=12 \mathrm{~V} \times 4 \mathrm{~mA}=48 \mathrm{~mW} \\
& \Delta \mathrm{~T}=\mathrm{P}_{\mathrm{D}} \times \mathrm{R}_{\theta \mathrm{JA}}=48 \mathrm{~mW} \times 140^{\circ} \mathrm{C} / \mathrm{W}=7^{\circ} \mathrm{C} \\
& \mathrm{~T}_{\mathrm{J}}=\mathrm{T}_{\mathrm{A}}+\Delta \mathrm{T}=25^{\circ} \mathrm{C}+7^{\circ} \mathrm{C}=32^{\circ} \mathrm{C}
\end{aligned}
$$

A worst-case estimate, $\mathrm{P}_{\mathrm{D}(\max )}$, represents the maximum allowable power level $\left(\mathrm{V}_{\mathrm{CC}(\max )}, \mathrm{I}_{\mathrm{CC}(\max )}\right)$, without exceeding $\mathrm{T}_{\mathrm{J}(\max )}$, at a selected $\mathrm{R}_{\theta \mathrm{JA}}$ and $\mathrm{T}_{\mathrm{A}}$.

Example: Reliability for $\mathrm{V}_{\mathrm{CC}}$ at $\mathrm{T}_{\mathrm{A}}=150^{\circ} \mathrm{C}$, package UA, using minimum-K PCB.

Observe the worst-case ratings for the device, specifically:
$\mathrm{R}_{\theta \mathrm{JA}}=165^{\circ} \mathrm{C} / \mathrm{W}, \mathrm{T}_{\mathrm{J}(\max )}=165^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{CC}(\max )}=24 \mathrm{~V}$, and $\mathrm{I}_{\mathrm{CC}(\max )}=17 \mathrm{~mA}$.
Calculate the maximum allowable power level, $\mathrm{P}_{\mathrm{D}(\max )}$. First, invert equation 3 :

$$
\Delta \mathrm{T}_{\max }=\mathrm{T}_{\mathrm{J}(\max )}-\mathrm{T}_{\mathrm{A}}=165^{\circ} \mathrm{C}-150^{\circ} \mathrm{C}=15^{\circ} \mathrm{C}
$$

This provides the allowable increase to $\mathrm{T}_{\mathrm{J}}$ resulting from internal power dissipation. Then, invert equation 2 :

$$
\mathrm{P}_{\mathrm{D}(\max )}=\Delta \mathrm{T}_{\max } \div \mathrm{R}_{\theta \mathrm{JA}}=15^{\circ} \mathrm{C} \div 165^{\circ} \mathrm{C} / \mathrm{W}=91 \mathrm{~mW}
$$

Finally, invert equation 1 with respect to voltage:

$$
\mathrm{V}_{\mathrm{CC}(\mathrm{est})}=\mathrm{P}_{\mathrm{D}(\max )} \div \mathrm{I}_{\mathrm{CC}(\max )}=91 \mathrm{~mW} \div 17 \mathrm{~mA}=5 \mathrm{~V}
$$

The result indicates that, at $\mathrm{T}_{\mathrm{A}}$, the application and device can dissipate adequate amounts of heat at voltages $\leq \mathrm{V}_{\mathrm{CC}(\mathrm{est})}$.
Compare $\mathrm{V}_{\mathrm{CC}(\text { est) }}$ to $\mathrm{V}_{\mathrm{CC}(\max )}$. If $\mathrm{V}_{\mathrm{CC}(\mathrm{est})} \leq \mathrm{V}_{\mathrm{CC}(\max )}$, then reliable operation between $\mathrm{V}_{\mathrm{CC}(\text { est })}$ and $\mathrm{V}_{\mathrm{CC}(\max )}$ requires enhanced $R_{\theta J A}$. If $V_{C C(e s t)} \geq V_{C C(\max )}$, then operation between $V_{C C(e s t)}$ and $\mathrm{V}_{\mathrm{CC}(\max )}$ is reliable under these conditions.

## Device Qualification Program

Contact Allegro for information.

## EMC (Electromagnetic Compatibility) Requirements

Contact your local representative for EMC results.

| Test Name | Reference Specification |
| :--- | :--- |
| ESD - Human Body Model | AEC-Q100-002 |
| ESD - Machine Model | AEC-Q100-003 |
| Conducted Transients | ISO 7637-1 |
| Direct RF Injection | ISO 11452-7 |
| Bulk Current Injection | ISO 11452-4 |
| TEM Cell | ISO 11452-3 |

## Product Selection Guide

Use the complete part numbers when ordering

| Part Number | Pb-Free | Packing ${ }^{\text {a }}$ | Package | Operating Ambient Temperature, $\mathrm{T}_{\mathrm{A}}$ ( ${ }^{\circ} \mathrm{C}$ ) | Output Level in <br> South (+) Field ${ }^{\text {b }}$ | Supply Current at Low Output, $\mathrm{I}_{\mathrm{CC}(\mathrm{L})}$ (mA) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| A1140ELHLT | - | Tape and Reel 3000 pieces/reel | Surface Moun | -40 to 85 | Low | 2 to 5 |
| A1140ELHLT-T | Yes | Tape and Reel, 3000 pieces/re | Surface Mount |  |  |  |
| A1140EUA | - | Bulk Bag, 500 pieces/bag | Through Hole |  |  |  |
| A1140EUA-T | Yes |  |  |  |  |  |
| A1140EUATI | - | Tape and Reel, 2000 pieces/reel |  |  |  |  |
| A1140EUATI-T | Yes |  |  |  |  |  |
| A1140LLHLT | - | Tape and Reel, 3000 pieces/reel | Surface Mount | -40 to 150 |  |  |
| A1140LLHLT-T | Yes |  |  |  |  |  |
| A1140LUA | - | Bulk Bag, 500 pieces/bag | Through Hole |  |  |  |
| A1140LUA-T | Yes |  |  |  |  |  |
| A1140LUATI | - | Tape and Reel, 2000 pieces/reel |  |  |  |  |
| A1140LUATI-T | Yes |  |  |  |  |  |
| A1141ELHLT | - | Tape and Reel, 3000 pieces/reel | Surface Mount | -40 to 85 | High |  |
| A1141ELHLT-T | Yes |  |  |  |  |  |
| A1141EUA | - | Bulk Bag, 500 pieces/bag | Through Hole |  |  |  |
| A1141EUA-T | Yes |  |  |  |  |  |
| A1141EUATI | - | Tape and Reel, 2000 pieces/reel |  |  |  |  |
| A1141EUATI-T | Yes |  |  |  |  |  |
| A1141LLHLT | - | Tape and Reel, 3000 pieces/reel | Surface Mount | -40 to 150 |  |  |
| A1141LLHLT-T | Yes |  |  |  |  |  |
| A1141LUA | - | Bulk Bag, 500 pieces/bag | Through Hole |  |  |  |
| A1141LUA-T | Yes |  |  |  |  |  |
| A1141LUATI | - | Tape and Reel, 2000 pieces/reel |  |  |  |  |
| A1141LUATI-T | Yes |  |  |  |  |  |

Continued on the next page....

## Sensitive Two-Wire Chopper-Stabilized Unipolar Hall Effect Switches

Continued from the previous page....

| Part Number | Pb-Free | Packing ${ }^{\text {a }}$ | Package | Operating Ambient Temperature, $\mathrm{T}_{\mathrm{A}}$ ( $\left.{ }^{\circ} \mathrm{C}\right)$ | Output Level in South (+) Field ${ }^{\text {b }}$ | Supply Current at Low Output, $\mathrm{I}_{\mathrm{CC}(\mathrm{L})}$ (mA) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| A1142ELHLT | - | Tape and Reel, 3000 pieces/reel | Surface Mount | -40 to 85 | Low | 5 to 6.9 |
| A1142ELHLT-T | Yes |  |  |  |  |  |
| A1142EUA | - | Bulk Bag, 500 pieces/bag | Through Hole |  |  |  |
| A1142EUA-T | Yes |  |  |  |  |  |
| A1142EUATI | - | Tape and Reel, 2000 pieces/reel |  |  |  |  |
| A1142EUATI-T | Yes |  |  |  |  |  |
| A1142LLHLT | - | Tape and Reel, 3000 pieces/reel | Surface Mount | -40 to 150 |  |  |
| A1142LLHLT-T | Yes |  |  |  |  |  |
| A1142LUA | - | Bulk Bag, 500 pieces/bag | Through Hole |  |  |  |
| A1142LUA-T | Yes |  |  |  |  |  |
| A1142LUATI | - | Tape and Reel, 2000 pieces/reel |  |  |  |  |
| A1142LUATI-T | Yes |  |  |  |  |  |
| A1143ELHLT | - | Tape and Reel, 3000 pieces/reel | Surface Mount | -40 to 85 | High |  |
| A1143ELHLT-T | Yes |  |  |  |  |  |
| A1143EUA | - | Bulk Bag, 500 pieces/bag | Through Hole |  |  |  |
| A1143EUA-T | Yes |  |  |  |  |  |
| A1143EUATI | - | Tape and Reel, 2000 pieces/reel |  |  |  |  |
| A1143EUATI-T | Yes |  |  |  |  |  |
| A1143LLHLT | - | Tape and Reel, 3000 pieces/reel | Surface Mount | -40 to 150 |  |  |
| A1143LLHLT-T | Yes |  |  |  |  |  |
| A1143LUA | - | Bulk Bag, 500 pieces/bag | Through Hole |  |  |  |
| A1143LUA-T | Yes |  |  |  |  |  |
| A1143LUATI | - | Tape and Reel, 2000 pieces/reel |  |  |  |  |
| A1143LUATI-T | Yes |  |  |  |  |  |

${ }^{\text {a Contact Allegro for additional packing options. }}$
${ }^{\text {b }}$ South ( + ) magnetic fields must be of sufficient strength.

## A1140/41/42/43

## Sensitive Two-Wire Chopper-Stabilized Unipolar Hall Effect Switches

Package LH, 3-Pin; (SOT-23W)


Package UA, 3-Pin SIP


Dimensions in inches
Metric dimensions ( mm ) in brackets, for reference only
A Dambar removal protrusion
B) Hall element

The products described herein are manufactured under one or more of the following U.S. patents: 5,045,920; 5,264,783; 5,442,283; 5,389,889; 5,581,179; 5,517,112; 5,619,137; 5,621,319; 5,650,719; 5,686,894; 5,694,038; 5,729,130; 5,917,320; and other patents pending.

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[^0]:    *Typical data taken at $\mathrm{T}_{\mathrm{A}}=25^{\circ}$

